


PCN Number:	20220208000.1			PCN Date:	February 16, 2022																														
Title:	Qualification of TIPI as an alternate Assembly site for select devices																																		
Customer Contact:	PCN Manager	Dept:	Quality Services																																
Proposed 1st Ship Date:	May 16, 2022	Estimated Sample Availability:	Date provided at sample request																																
Change Type:																																			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																														
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																														
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																														
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																														
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																														
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process																														
PCN Details																																			
Description of Change:																																			
Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for the select devices listed below. Construction differences are noted below:																																			
<table border="1"> <thead> <tr> <th>What</th> <th>ASEK</th> <th>TIEM</th> <th>TITL</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#1800008161</td> <td>8095183</td> <td>4209640</td> <td>4222198</td> </tr> <tr> <td>Mount Compound</td> <td>SID#1400013111</td> <td>8001746</td> <td>4211470</td> <td>4211470</td> </tr> <tr> <td>Lead Finish</td> <td>Matte Sn</td> <td>Matte Sn</td> <td>NiPdAu</td> <td>NiPdAu</td> </tr> <tr> <td>Bond wire/diameter</td> <td>Au/1.0 mil</td> <td>Au/1.0 mil</td> <td>Cu/0.8 mil</td> <td>Cu/0.8 mil</td> </tr> <tr> <td>ECAT</td> <td>G3</td> <td>G3</td> <td>G4</td> <td>G4</td> </tr> </tbody> </table>						What	ASEK	TIEM	TITL	TIPI	Mold Compound	SID#1800008161	8095183	4209640	4222198	Mount Compound	SID#1400013111	8001746	4211470	4211470	Lead Finish	Matte Sn	Matte Sn	NiPdAu	NiPdAu	Bond wire/diameter	Au/1.0 mil	Au/1.0 mil	Cu/0.8 mil	Cu/0.8 mil	ECAT	G3	G3	G4	G4
What	ASEK	TIEM	TITL	TIPI																															
Mold Compound	SID#1800008161	8095183	4209640	4222198																															
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ECAT	G3	G3	G4	G4																															
Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part number</u> , for example; <u>DP83848CVV/NOPB</u> – can ship with both Matte Sn and NiPdAu.																																			
Reason for Change:																																			
Supply continuity																																			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																																			
None																																			
Impact on Environmental Ratings																																			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																																			
RoHS		REACH		Green Status																															
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change																															
<input type="checkbox"/>		<input type="checkbox"/>		<input type="checkbox"/>																															
<input type="checkbox"/>		<input type="checkbox"/>		<input type="checkbox"/>																															
Changes to product identification resulting from this PCN:																																			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City																																
ASEK	ASF	TWN	Kaohsiung																																
TIEM	CU6	MYS	Melaka																																
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City																																

TIPI	PHI	PHL	Baguio City
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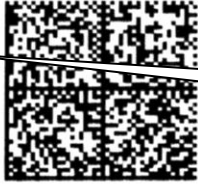
Sample product shipping label (not actual product label)

 **TEXAS INSTRUMENTS**
 MADE IN: Malaysia
 2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750


 G4



(1P) SN74LS07NSR
 0000 (D) 0336
 (31T) LOT: 3959047
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CS0: SHE (21L) CCO: USA
 (22L) AS0: MLA (23L) ACO: MYS

G4: NiPdAu
 G3: Matte Sn

Product Affected:

DP83848CVV/NOPB	DP83848EVVX/NOPB	DP83848IEVVX/NOPB	DP83848IVVX/NOPB
DP83848CVVX/NOPB	DP83848IEVV/NOPB	DP83848IVV/NOPB	DP83848IVVX/S7002477
DP83848EVV/NOPB			



TI Information
 Selective disclosure

Qualification Results
 Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration
PC	Preconditioning	(MSL3 @ 260C peak +/-0C)
CDM	ESD CDM	+/- 1000V
ED	Electrical Characterization	Per Datasheet Parameters
HAST	**Biased HAST	130C/85%RH/33.3 psia (96 Hrs.), Vddmax
HBM	ESD HBM	+/-4000V
LU	Latch-up	(per JESD78)-125C
MISC	Bond Pad Cratering Check	During MQ
MISC	Bond Pad Cratering Check	Post 500 Cycles
MQ	Manufacturability (Assembly)	(per mfg. Site specification)
MSL	Thermal Path Integrity	(level 3 @ 260C +/-0C)
PD	Physical Dimensions	(per mechanical drawing)
TC	**T/C -65C/150C	-65C/+150C (500, Cycles)
UHAST	**Unbiased HAST	130C/85%RH/33.3 psia (96 Hours)
WBP	Bond Pull	76 Wire, 3 units min
WBS	Ball Bond Shear	76 balls, 3 units min
XRAY	X-ray	(top side only)

Type	Test Name / Condition	Duration
BP	Post 500 TC Bond Pull	30 ball bonds, min. 5 units

- QBS: Qual By Similarity
- Qual Device DP83848EVV/NOPB is qualified at LEVEL3-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210316-139150

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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